



Dear Valued Customer

Issue date: March 2026 / TG131

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LSIs Production Headquarters
ROHM Co., Ltd.

Notification of Product/Process Change
Doc. No.: 1026004

This letter intends as a formal notification of change to products which are currently supplied by ROHM Co., Ltd.

ROHM Co., Ltd. requires customers to provide acknowledgment of the receipt of this notification within 30 days from the date of this notice. Lack of acknowledgment of this notice within 30 days is considered as acceptance of the change.

After acknowledgement of the customer, lack of additional response within 90 day period constitutes acceptance of the change according to JEDEC Standard J-STD-046.

Your understanding and cooperation would be highly appreciated.

Issue Date: March 2, 2026

Issue Date: March 27, 2026

Title of change	Change in wafer factory from ROHM Headquarters to ROHM Apollo Chikugo and change in packaging materials due to production base reorganization.		
Affected product(s)	Manufacturer part number		Customer part number
	See Attachment		See Attachment
Detailed description of change	Before		After
	Front-End Process: ROHM Headquarters 0.35μm CMOS. Back-End Process: See Attachment.		Front-End Process:ROHM Apollo Chikugo 0.35μm CMOS. Wire material change models feature thicker PAD metal. Back-End Process: See Attachment.
Reason for change	We will restructure low-utilization, small-scale production lines and standardize materials to advance structural reforms that ensure a stable supply to our customers over the long term.		
Anticipated impact on quality	This change will have no impact on product quality.		
Identification of change	It can be identified by the internal model name on the product label.		
Planned first ship date		September 30, 2026	Sample available schedule : March 2, 2026
Comments			
Supplier contact	Please contact the local ROHM sales office or the authorized distributor.		
Notes			